

IBM Power Systems

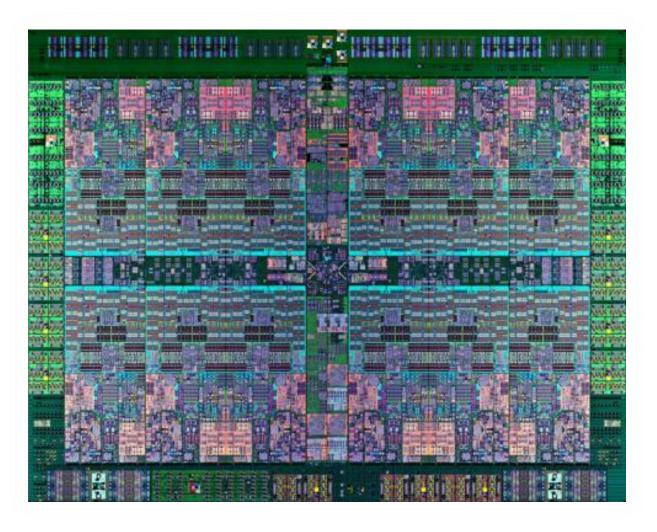
Power Systems Hardware: Today and Tomorrow

November 2015

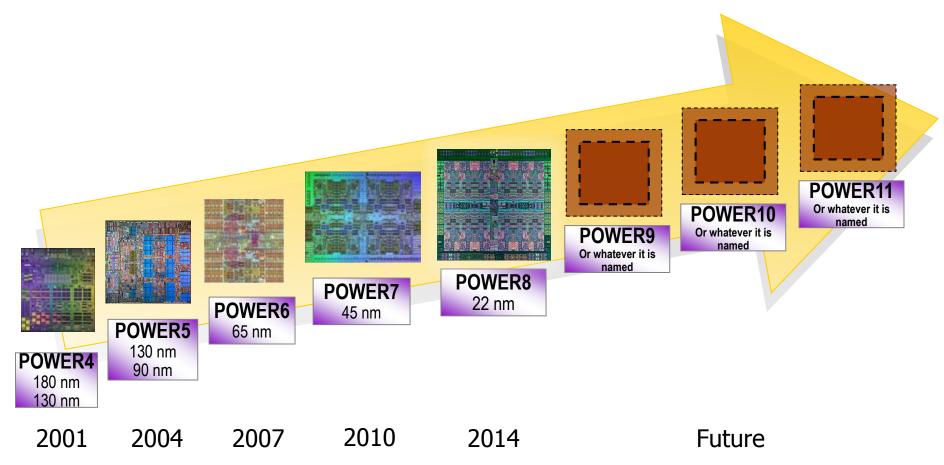
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POWER8 Chip



Processor Technology Roadmap



Processor Chip Comparisons

	POWER5 PC 2004		POWER7 2010	POWER7+ 2012	POWER8	
Technology	130nm SOI	65nm SOI	45nm SOI eDRAM	32nm SOI eDRAM	22nm SOI eDRAM	
Compute						
Cores	2	2	8	8	12	
Threads	SMT2	SMT2	SMT4	SMT4	SMT8	
Caching						
On-chip	1.9MB (L2)	8MB (L2)	2 + 32MB (L2+3)	2 + 80MB (L2+3)	6 + 96MB (L2+3)	
Off-chip	36MB (L3)	32MB (L3)	None	None	128MB (L4)	
Bandwidth						
Sust. Mem.	15GB/s	30GB/s	100GB/s	100GB/s	230GB/s	
Peak I/O	6GB/s	20GB/s	40GB/s	40GB/s	96GB/s	

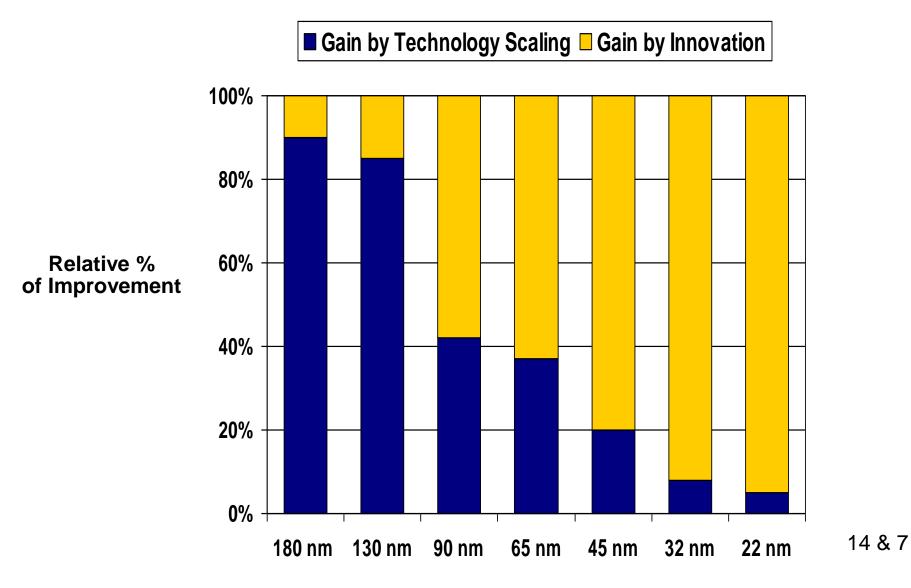
Processor Designs

	POWER5+	POWER6	POWER7	POWER7+	POWER8
Max cores	4	2	8	8	12
Technology	90nm	65nm	45nm	32nm	22nm
Size	245 mm ²	341 mm ²	567 mm ²	567 mm²	650 mm ² *
Transistors	276 M	790 M	1.2 B	2.1 B	4.2 B *
Frequencies	1.9 GHz	4 - 5 GHz	3 – 4 Up to 4.4 GHz GHz		Up to 4.1 GHz **
SMT (threads)	2	2	4	4	8
L2 Cache	1.9MB Shared	4MB / Core	256KB / core	256KB / core	512KB/core
L3 Cache	36MB	32MB	4MB / Core On chip	10MB / Core On chip	8MB / Core On chip
L4 Cache					Up to 128MB
Bandwidth Sust memory Peak I/O	15GB/s 6GB/s	30GB/s 20GB/s	100GB/s 40GB/s	100GB/s 40GB/s	230GB/s 96GB/s

Processor Designs

	POWER4	POWER4+	POWER5	POWER5+	POWER6	POWER7	POWER7+	POWER8
Max cores	2	2	2	4	2	8	8	12
Technology	180nm	130nm	130nm	90nm	65nm	45nm	32nm	22nm
Size	412mm ²	mm ²	389 mm ²	245 mm ²	341 mm ²	567 mm ²	567 mm ²	650 mm ² *
Transistors	170 M	180 M	276 M	276 M	790 M	1.2 B	2.1 B	4.2 B *
Frequencies	1.3 GHz	1.9 GHz	1.65-1.9 GHz	1.9-2.2 GHz	3 - 5 GHz	3 – 4.25 GHz	Up to 4.4 GHz	3 4.35 GHz
SMT (threads)	1	1	2	2	2	4	4	8
L2 Cache	1.4 MB Shared	1.5 MB Shared	1.9MB Shared	1.9MB Shared	4MB / Core	256KB / core	256KB / core	512KB/core
L3 Cache	32MB	32MB	36MB	36MB	32MB	4MB / Core On chip	10MB / Core On chip	8MB / Core On chip
L4 Cache								Up to 128MB
Bandwidth Sust memory Peak I/O	6GB/s 2GB/s	6GB/s 2GB/s	15GB/s 6GB/s	15GB/s 6GB/s	30GB/s 20GB/s	100GB/s 40GB/s	100GB/s 40GB/s	230GB/s 96GB/s

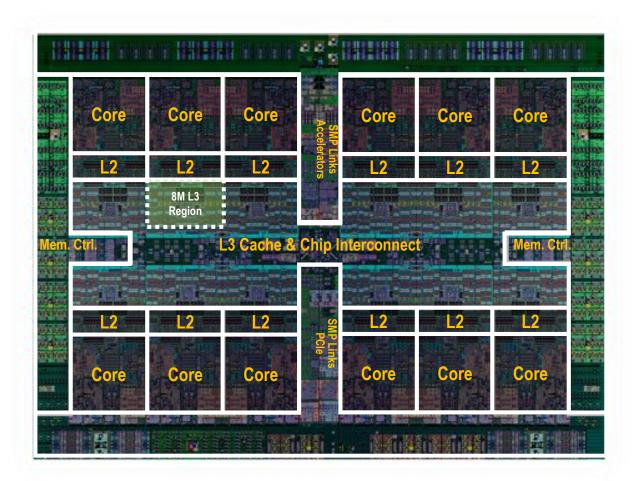
Innovation Drives Performance



POWER8 Chip Packaging

Technology

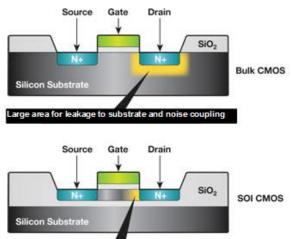
- 22nm SOI, eDRAM, 650mm2
- 15-layers = great bandwidth



IBM

World Class 22nm Semiconductor Technology

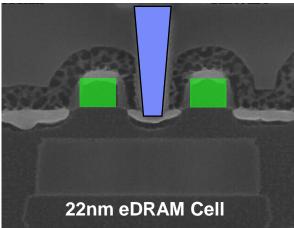
Silicon On Insulator -Faster Transistor, Less Noise



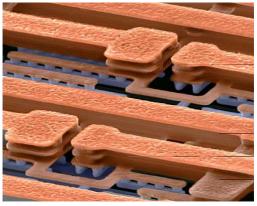
Small area for leakage and noise coupling

On-chip eDRAM

- 6x latency improvement
- No off-chip signaling rqmt
- 8x bandwidth improvement
- 3x less area than SRAM
- 5x less energy than SRAM



22nm 15-layer copper wire



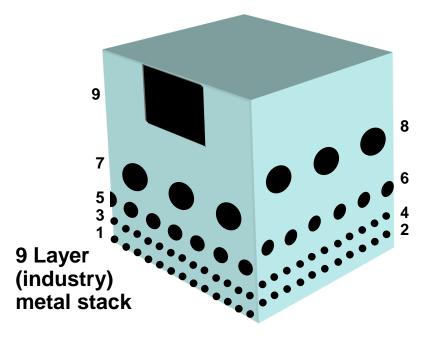
Dense interconnect

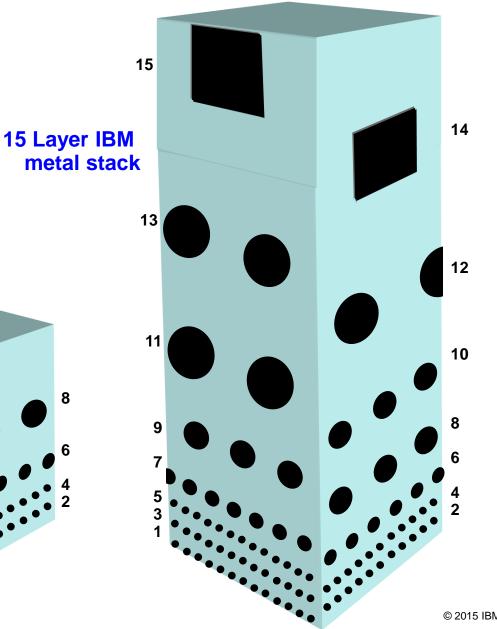
- Faster connections
- Low latency distance paths
- High density complex circuits
- 2X wire per transistor

IBM 22nm Technology

Low level wires used for dense local circuit interconnect.

Top level wires used for for power distribution, clocks, and off-chip signaling.





POWER8 Chip Packaging

Cores

- 12 cores (SMT8)
- 8 dispatch, 10 issue, 16 exec pipe
- 2X internal data flows/queues
- Enhanced prefetching

Caches

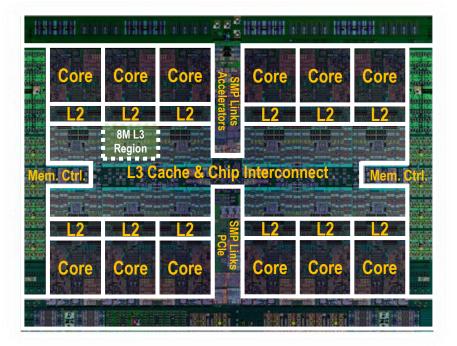
- 64K Data cache (L1)
- 512 KB SRAM L2 / core
- 96 MB eDRAM shared L3
- Up to 128 MB eDRAM L4 (off-chip)

Accelerators

- Crypto & memory expansion
- Transactional Memory
- Data Move / VM Mobility

Bus Interfaces

- Integrated PCIe Gen3
- SMP Interconnect
- CAPI



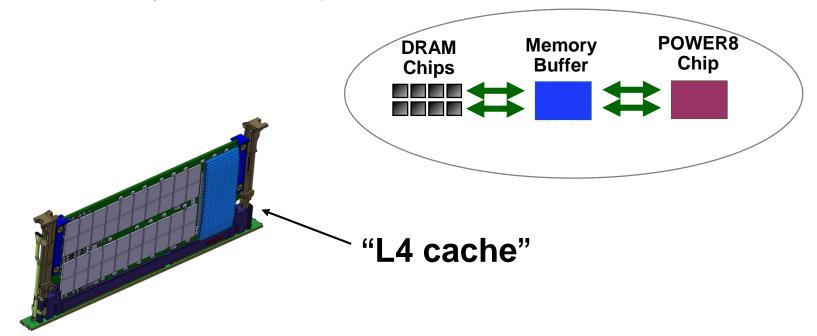
Energy Management

- On-chip Power Management Micro-controller
- Integrated Per-core VRM
- Critical Path Monitors

Memory

- Dual memory Controllers
- 230 GB/sec Sustained bandwidth

POWER8 Memory Buffer Chip



Intelligence Moved into Memory

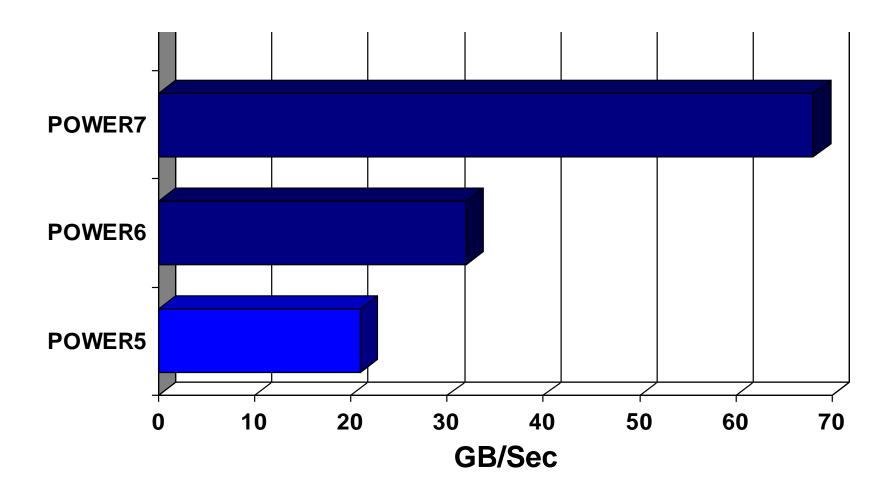
Previously on POWER7+ chip onto buffer

Processor Interface

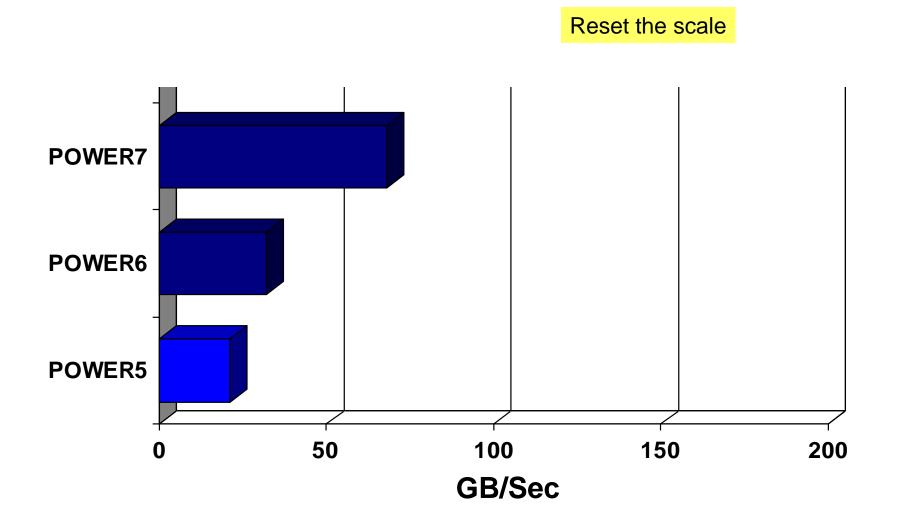
• High speed interface

Performance Value

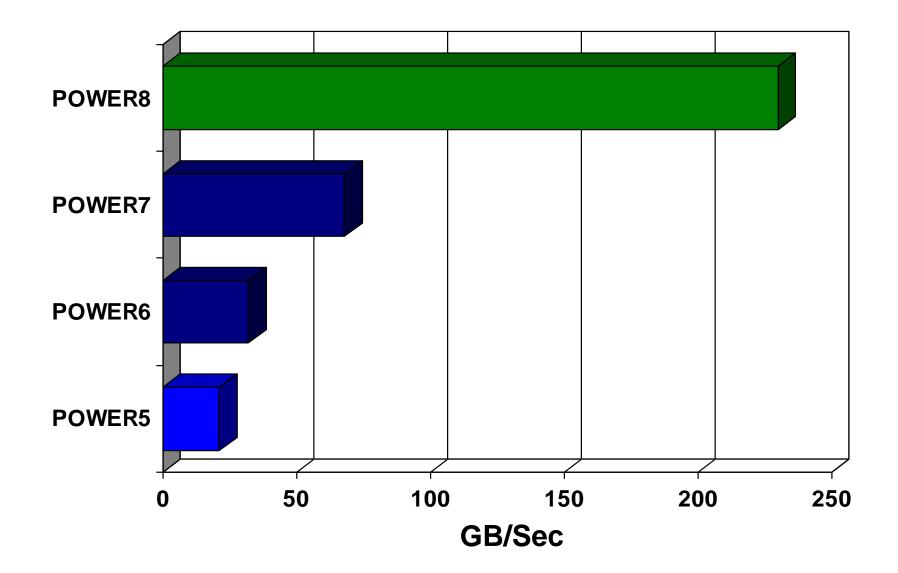
Memory Bandwidth per Socket



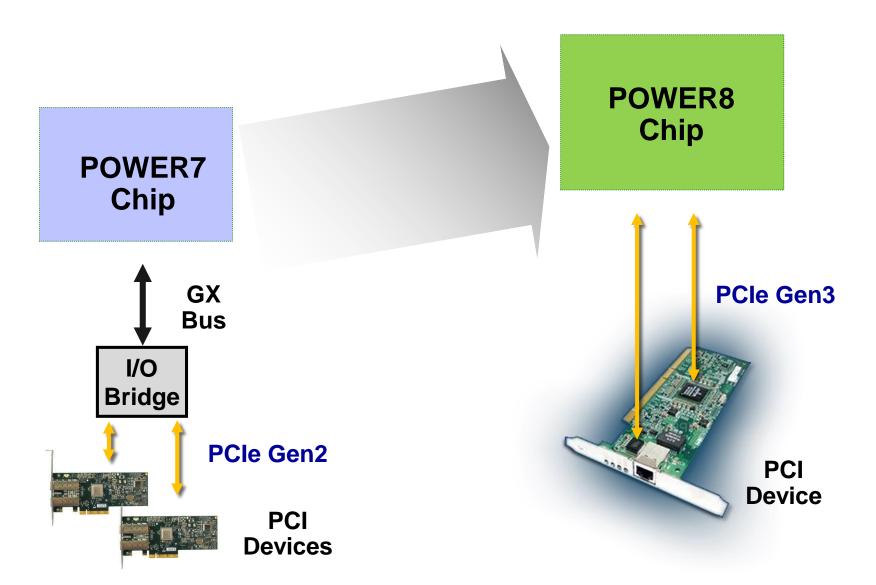
Memory Bandwidth per Socket



POWER8 Memory Bandwidth per Socket

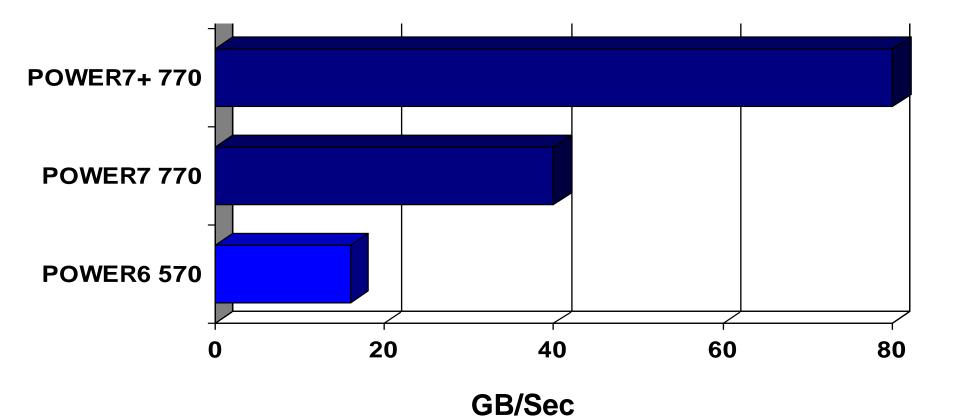


POWER8 Integrated PCI Gen 3



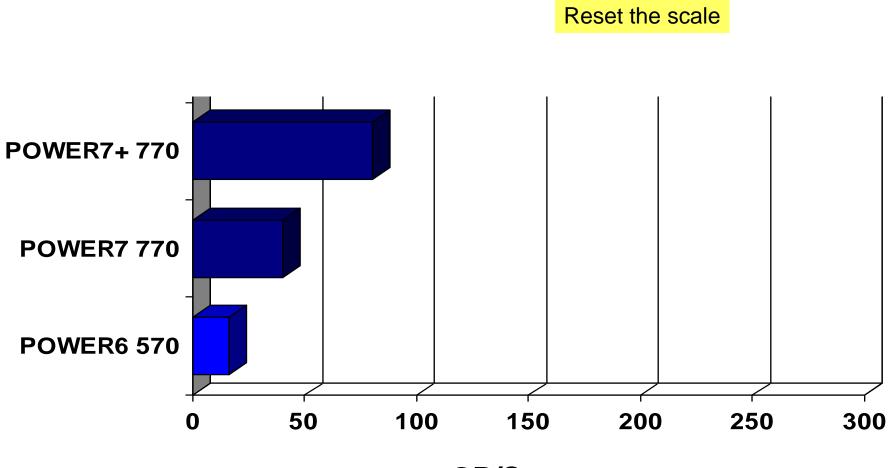
Power 770/780 Node I/O Bandwidth

(System node or processor enclosure or CEC drawer)



Power 770/780 Node I/O Bandwidth

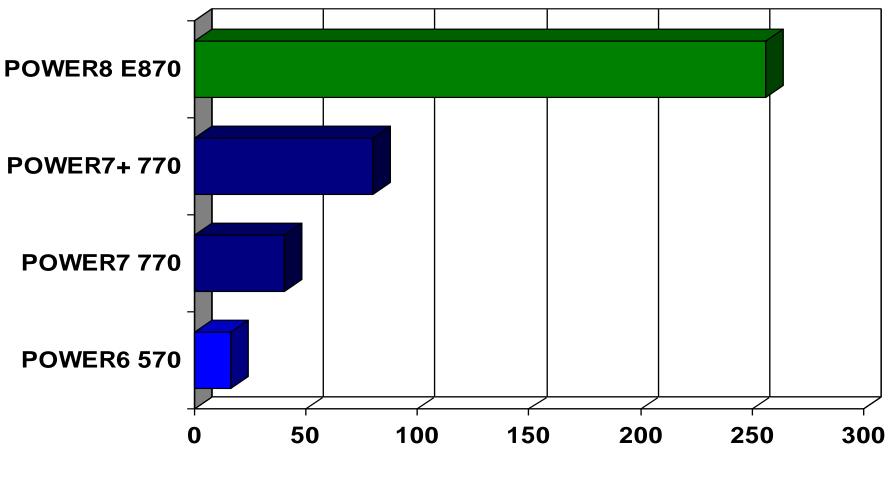
(System node or processor enclosure or CEC drawer)



GB/Sec

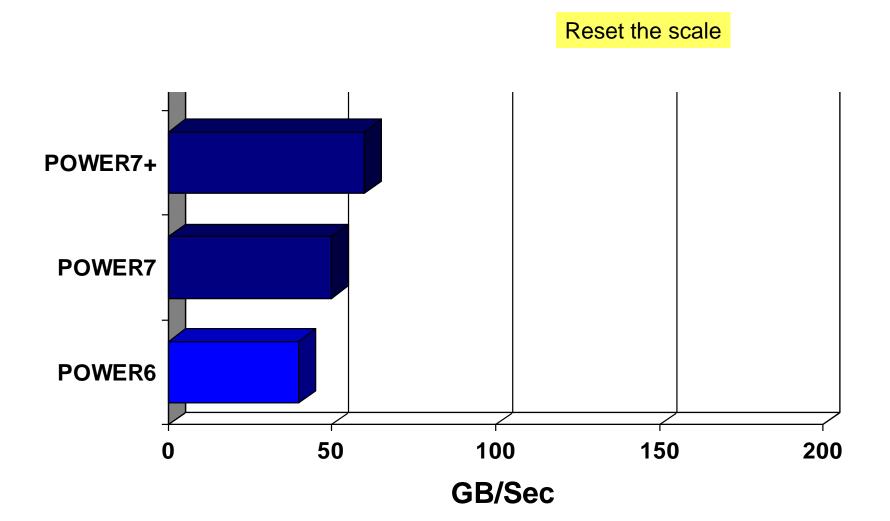
E870/E880 Node I/O Bandwidth

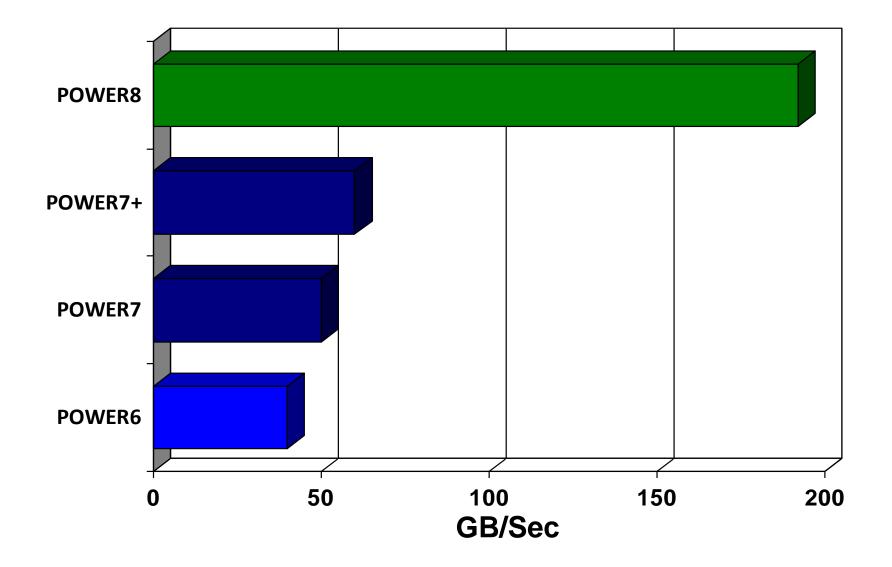
(System node or processor enclosure or CEC drawer)



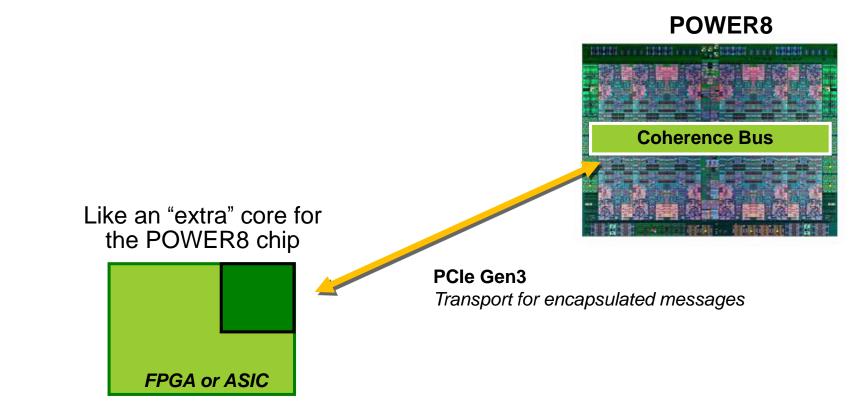
GB/Sec

IO Bandwidth Comparing 2-Socket Servers





POWER8 CAPI (Coherent Accelerator Processor Interface)



Customizable Hardware / Application Accelerator

- Specific system SW, middleware, or user application
- Written to durable interface

First CAPI Solution Example

High speed, fast response, social application – example Twitter

Enabled by in-memory NoSQL, distributed hash tables

Was initially implemented on x86 servers, but limited DRAM memory meant LOTS of servers resulting in a costly, complex infrastructure

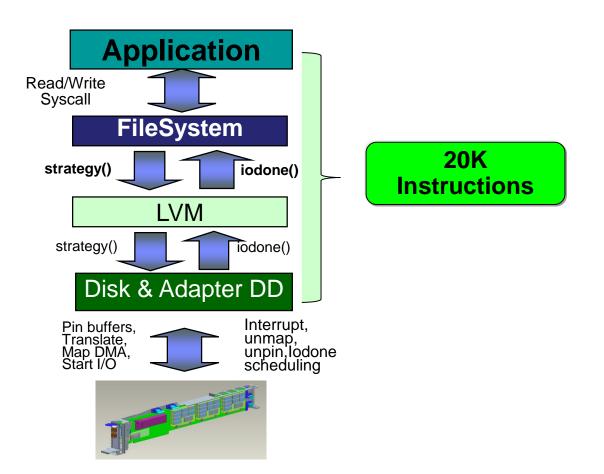


One 2-socket, 2U server PLUS one FlashSystem Drawer replaced 24 x86 servers

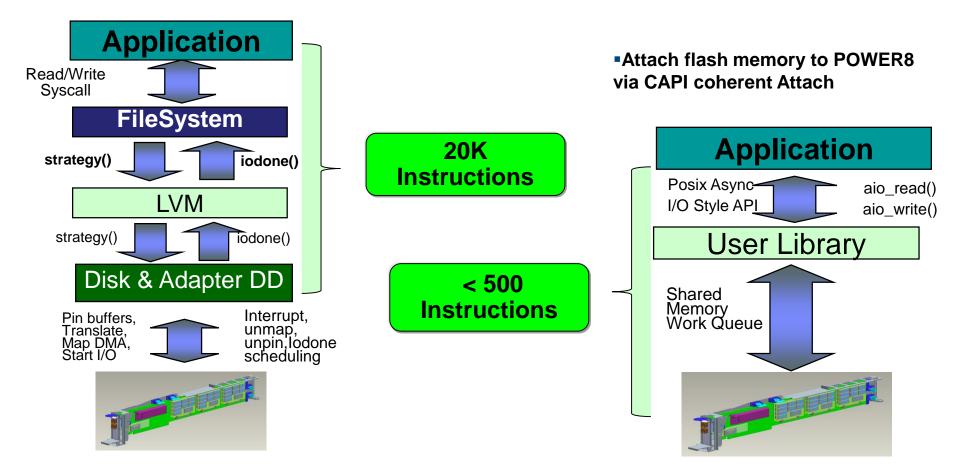
Much lower cost of acquisition Much smaller foot print, less energy Much lower operational cost



Example: CAPI Attached Flash Optimization

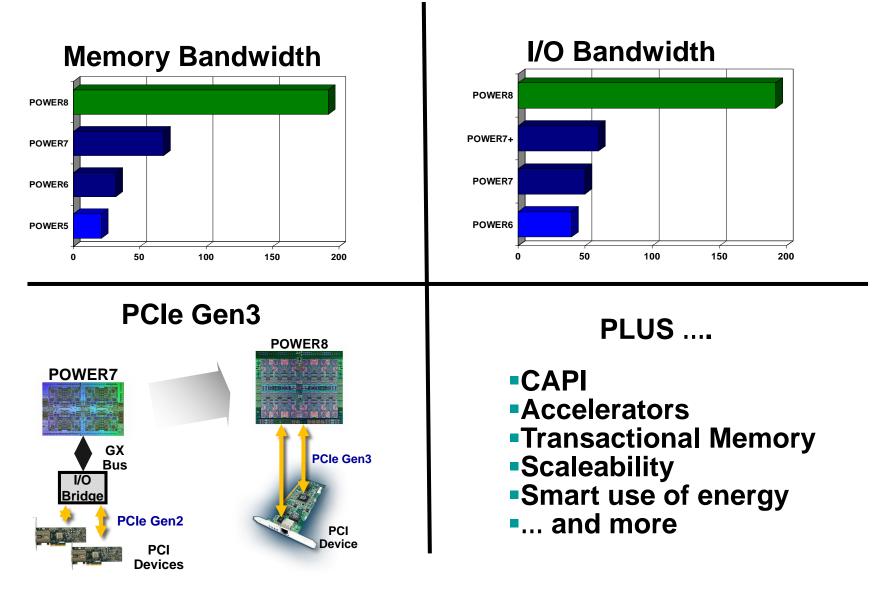


Example: CAPI Attached Flash Optimization

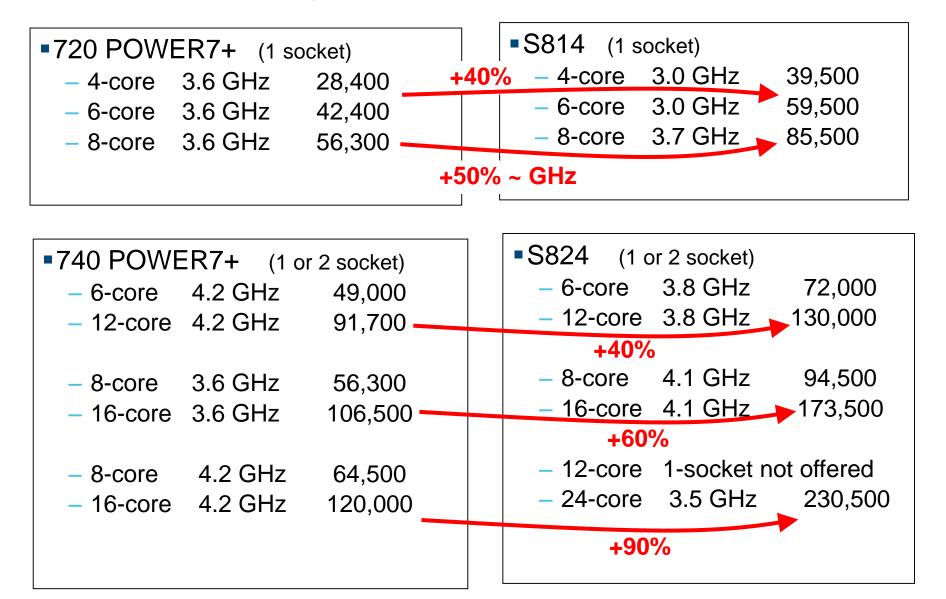


- Issues Read/Write Commands from applications to eliminate 97% of instruction path length CAPI Flash controller Operates in User Space
- Saves 10 Cores per 1M IOPs

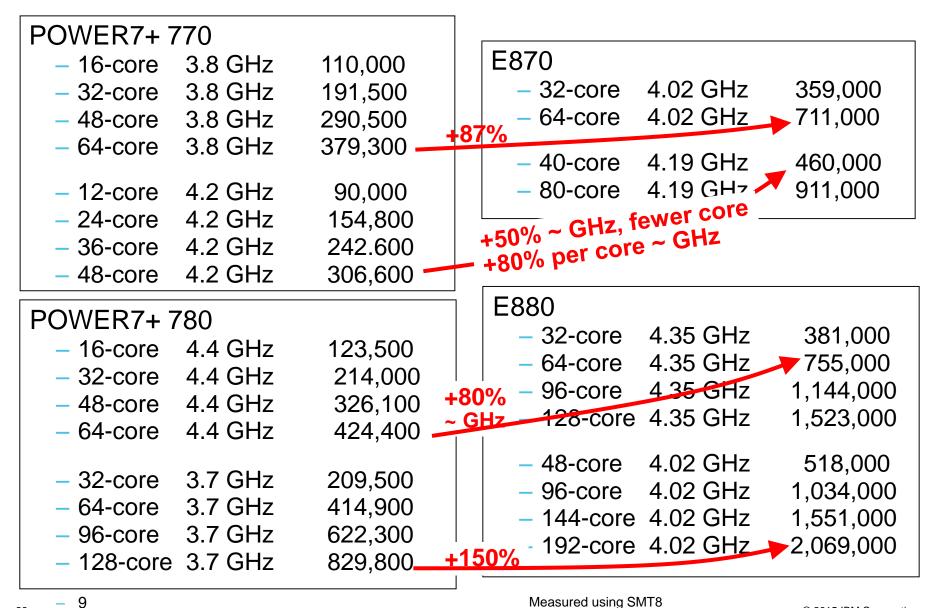
POWER8 Leapfrogs



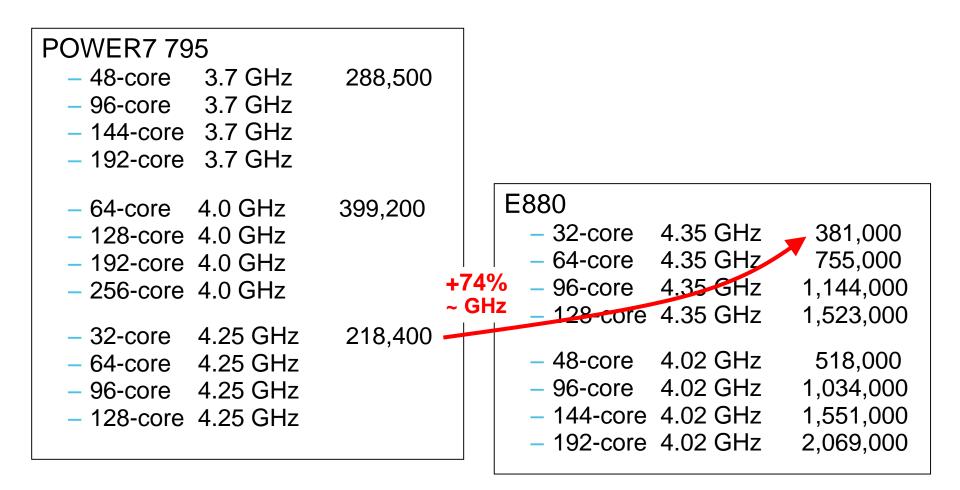
Scale-out CPW Comparisons



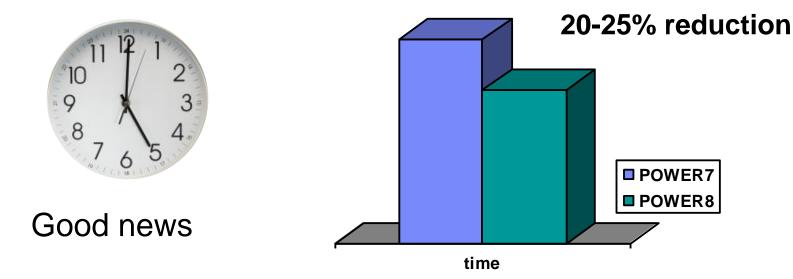
CPW



CPW



"Single-thread-oriented" Workloads and POWER8 Technology



Because per core performance improving ...

Compared to POWER7/POWER7+, POWER8 chips with similar GHz run 20-25% faster from a wall clock perspective ASSUMING NOT I/O BOUND



A New Generation of IBM Power Systems



Designed for Big Data

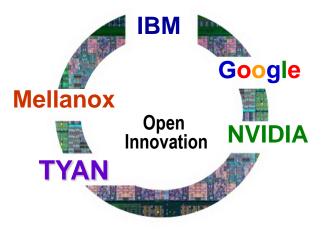
Superior Cloud Economics



Open Innovation Platform



OpenPOWER Consortium



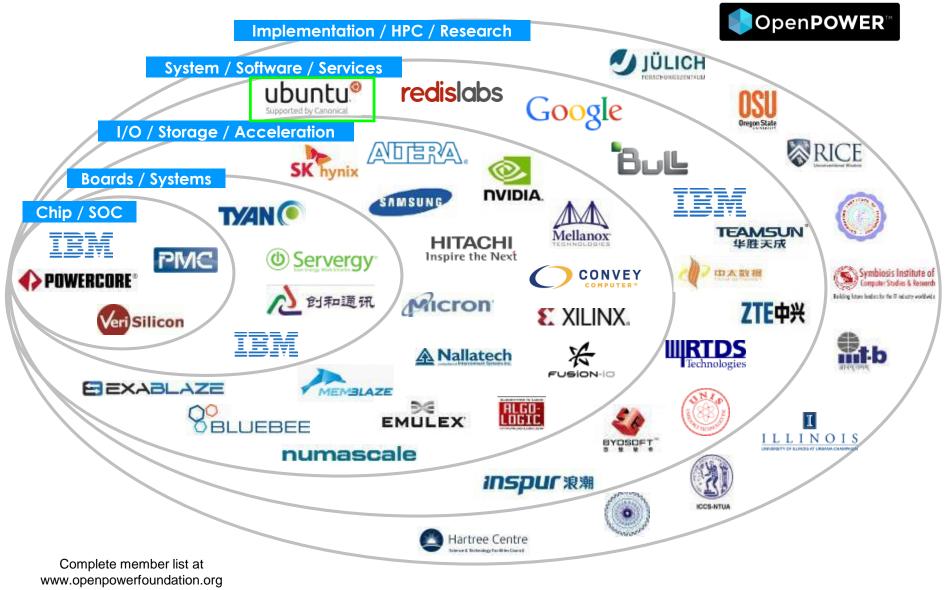
- Collaborative innovation for highly advanced systems
- Produce open hardware, software, firmware and tools
- Expand industry skills and investment for Power ecosystem
- Provide alternative architectures

Google® Mother Board using POWER8 Technology

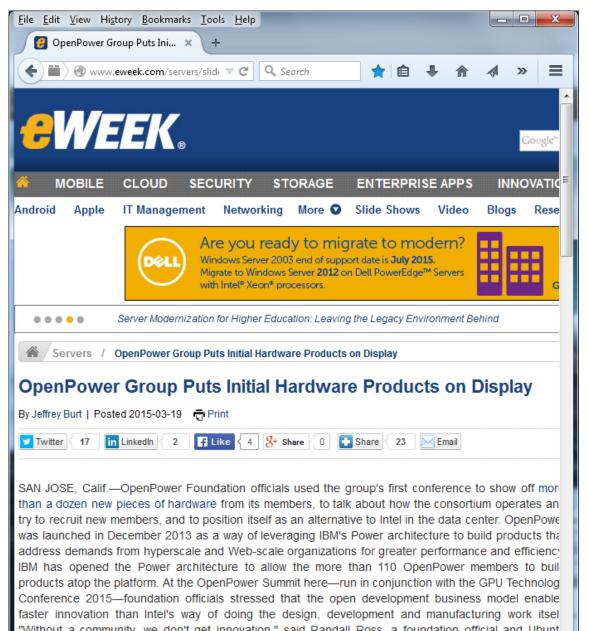


Development board previewed by Google at April 2014 POWER8 announcement

Building collaboration and innovation at all levels

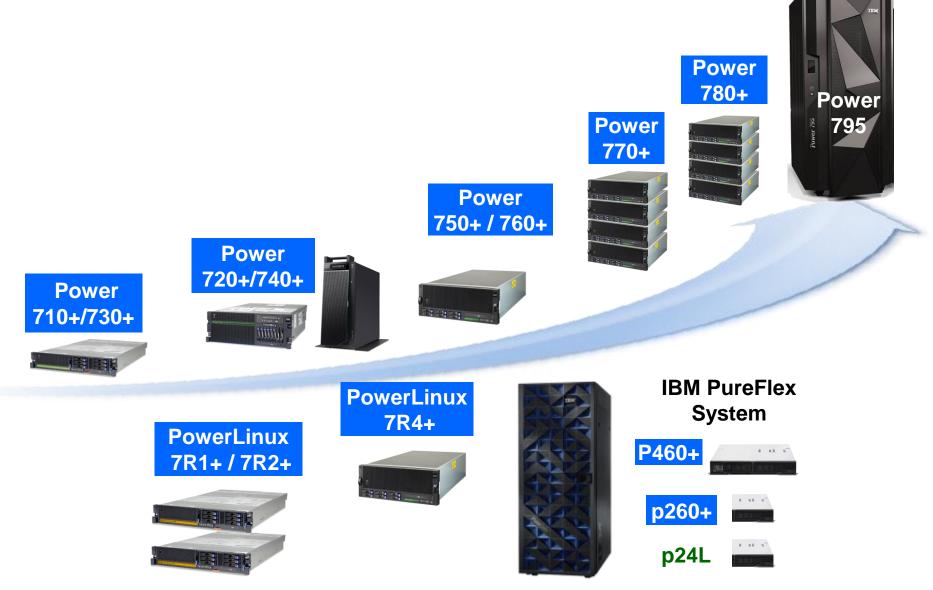


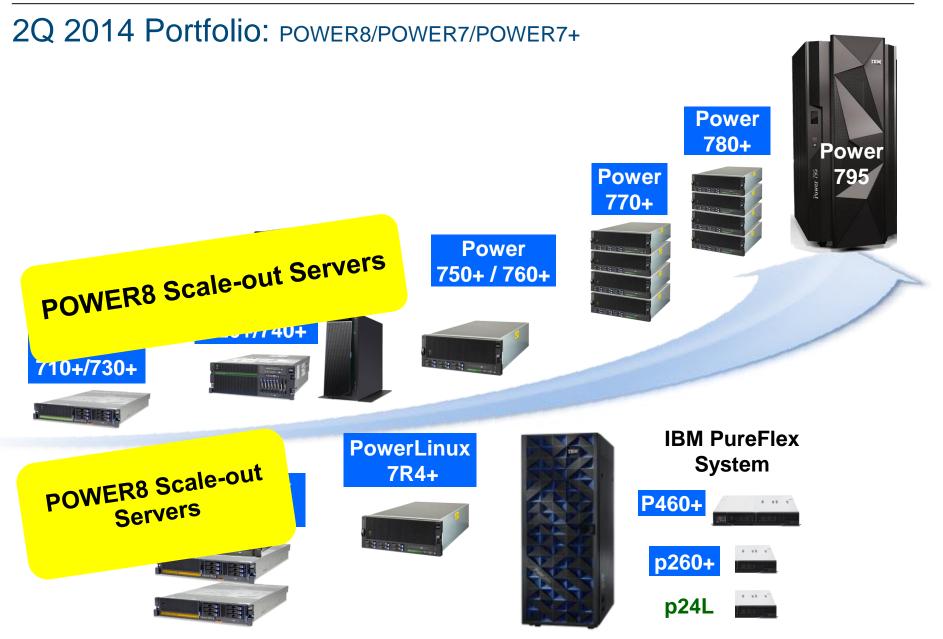
OpenPower Article in eWEEK - March 2015

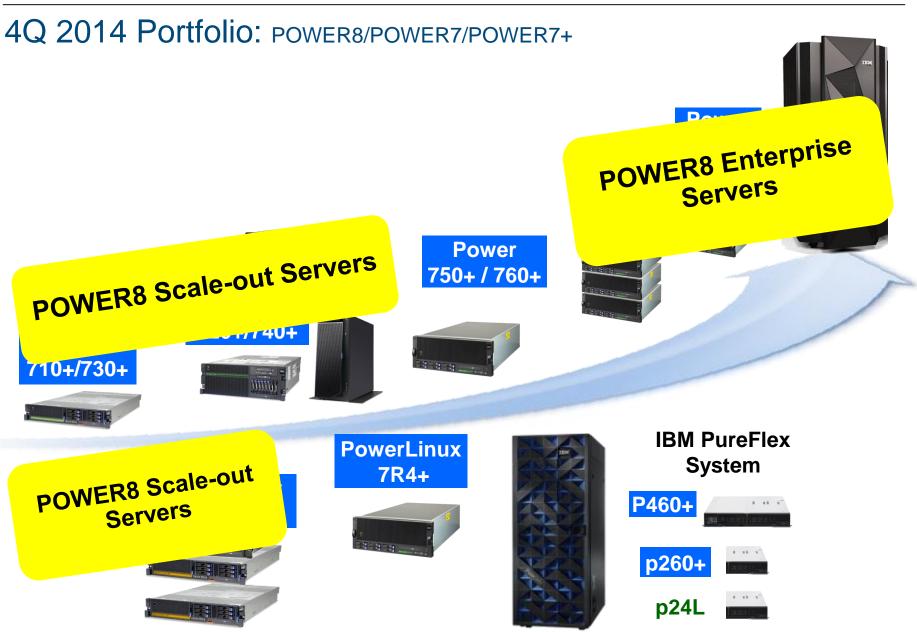


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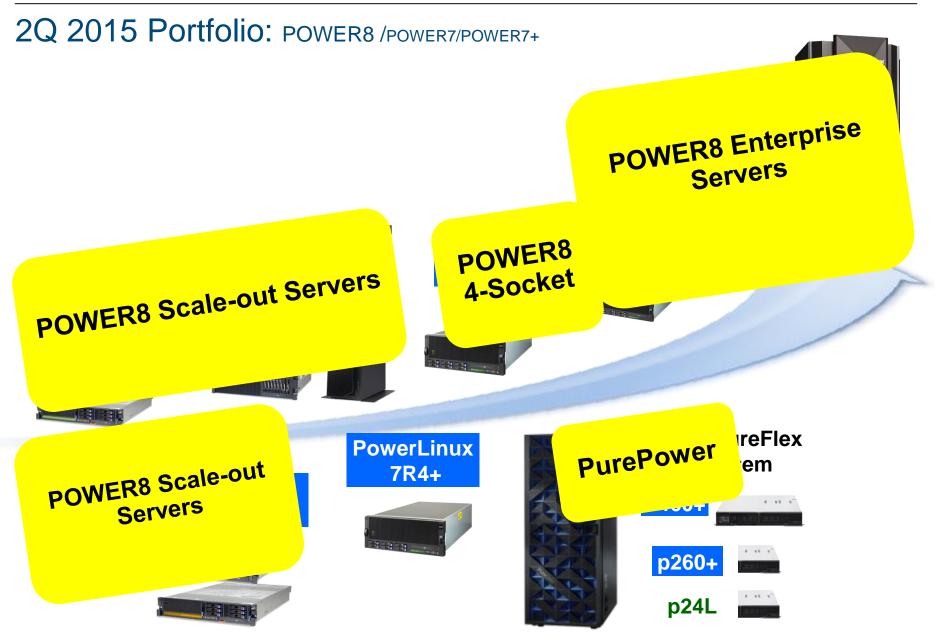
1Q 2014 Portfolio: power7/power7+

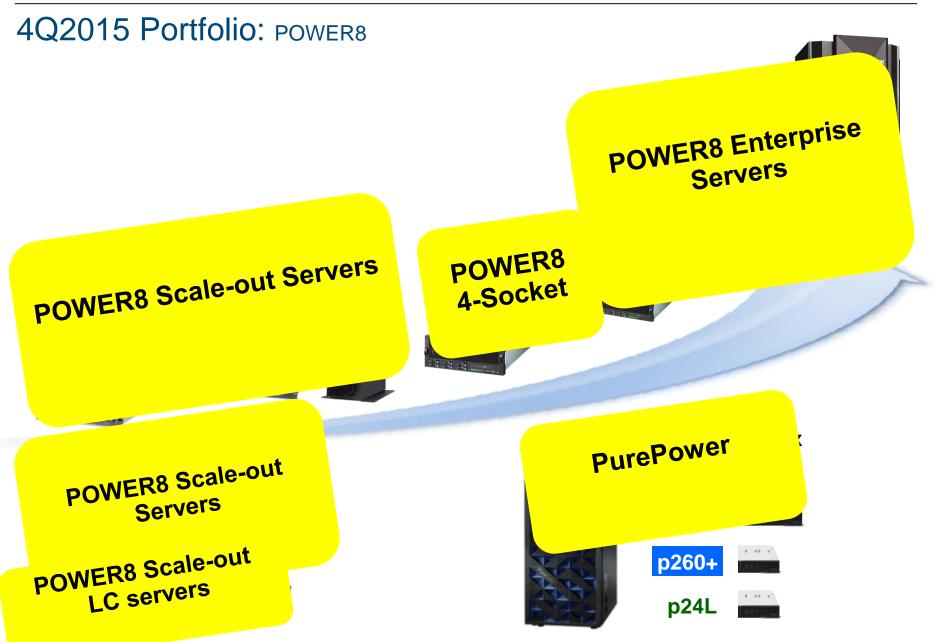




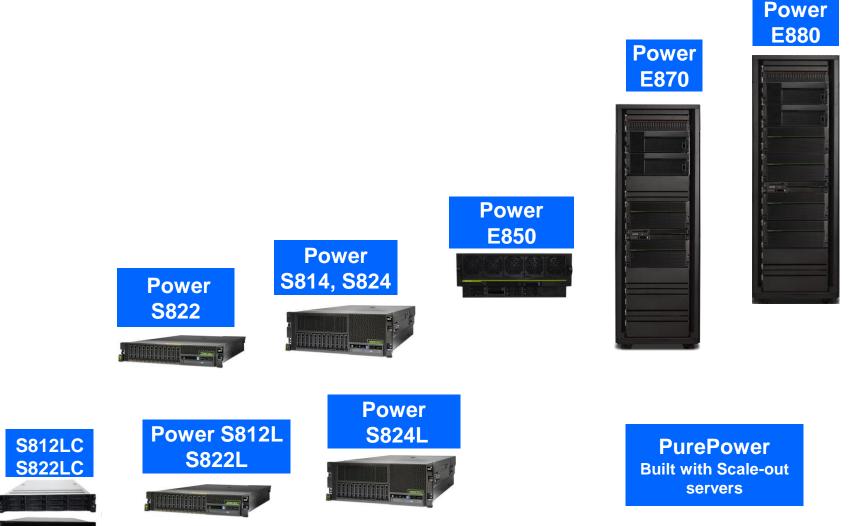


TRM

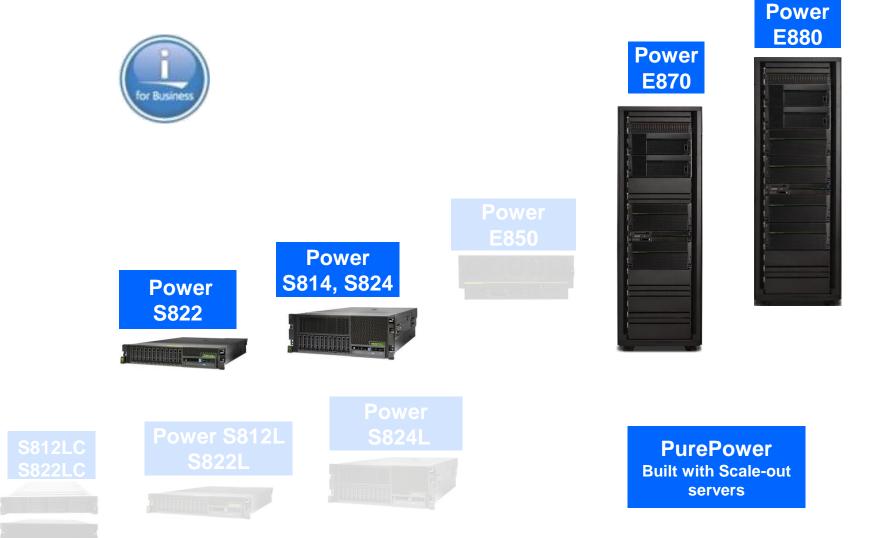




POWER8 Product Line 4Q 2015



POWER8 Product Line – IBM i Focus





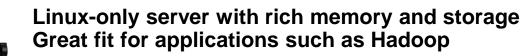
Scale-out

Scale-out Servers (LC line not shown)

S824 (2 socket, 4U)	AIX (I BUSINES) LINUX
S824L (1 socket, 4U)	Linux
S814 (1 socket, 4U)	AIX (IC BUSINESS) LINUX
S812L (1 socket, 2U)	Linux
S822 (2 socket, 2U)	AIX (Dr Busines) (LINUX
S822L (2 socket, 2U)	Linux

Linux Cluster Models Announcing October 2015

Bringing the benefits of the OpenPOWER Community to the IBM Power Systems Portfolio



2U, 1 socket up to 10 cores, up to 1TB memory, up to 14 disk/SSD (up to 112TB), 4 PCIe slots Power KVM or bare metal



Power S812LC

Power S822LC

Linux-only server with rich memory a focus on GPU capability



2U, 2 socket up to 20 cores, up to 1TB memory, up to two GPU, 5 PCIe slots Power KVM or bare metal



Scale-out Servers with IBM i support (or AIX/Linux support)



S814 (1 socket, 4U)
- 4 core (P05 IBM i software tier)
- 6 or 8 core (P10 IBM i software tier)



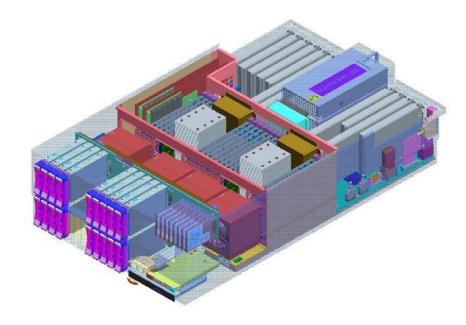
S824 (2 socket, 4U) – 6/12 or 8/16 or 24 core – P20 IBM i software tier



S822 (2 socket, 2U) – 6/8/10 or 12/16/20 core – P10 IBM i software tier

POWER8 4U 2-Socket Server

- 4U Form Factor
- I to 2 Sockets (Up 24 Cores)
- Up to 2TB Memory
 - With 8GB DDR3 DIMMs
- 11 PCIe Gen3 Slots / Hot Plug
 - Hot plug support
 - I PCIe slot reserved for Ethernet
- Up to 18 SFF Bays
 - Optional RAID support
- Up to 8 1.8" SSDs
- Integrated PCIe Gen3 SAS controller w/ optional write cache



2S2U Scale-out System

Power S822

- Single Socket populated
 - Cores: 6 (3.8 GHz) or 10 (3.4 GHz) or 8 (4.1 GHz)
 - Memory: Up to 512 GB *
 - PCIe Slots: 6 PCIe Gen3 LP (Hotplug)
- Both Sockets populated
 - Cores: 12 (3.8 GHz) or 20 (3.4 GHz) or 16 (4.1 GHz)
 - Memory: Up to 1 TB *
 - PCIe Slots: 9 PCIe Gen3 LP (Hotplug)
- Ethernet: Choice of 1Gb or 10Gb PCIe adapter
- Integrated ports: USB (4), Serial (1), HMC (2)
- Internal Storage
 - DVD
 - 12 SFF Bays -- Split Backplane: 6 + 6
 - or 8 SFF Bays & 6 1.8" SSD Bays with Easy Tier with 7GB write cache
- Hypervisor: PowerVM
- OS: AIX, Linux (IBM i added Oct 2015)
 - * Half this memory maximum with 4.1GHz cores (no 64GB DIMMs) due to air cooling limitations. See following chart with additional cooling limitations and for SOD for water cooling.





POWER8 4U Scale-out System

Power S814/S824

- Form Factor: 4U or Tower*
- One or two sockets **
 - Cores: 1 socket: 4–8, 2 socket: 6-24
 - GHz: 3.0 4.1
- Memory: Up to 1TB per socket***
- PCIe Slots: 7 or 11 PCIe Gen3 Full-high (Hotplug)
 - PCIe I/O drawer: adds up to 20 more slots (Hotplug)**
- Integrated Storage
 - POWERFUL SAS controllers up to 7GB cache
 - 12 18 SFF Bays*** + 8 SSD Bays****
 - Optional add 24 more SAS bays***
 - DVD
- Hypervisor: PowerVM
- OS: AIX, IBM i, Linux
 - IBM i 7.1 or later (P05 P20 software tier)

- ** See model specifics for valid combinations of sockets, cores, GHz
- *** 4-core S814 has entry level server limitation
- **** 8 SSD bays only with 2-socket server





3 Yr Warranty

^{*} Tower only for 4-core or 6-core S814

POWER8 1S4U Scale-out System

Power S814

- Form Factor: 4U or Tower
- Single Socket
 - Cores: 4 (3.0 GHz), 6 (3.0 GHz) or 8 (3.7 GHz)
 - Memory: Up to 512 GB (6-core or 8-core)
 - Slots: 7 PCle Gen3 Full-high (Hotplug)
- •PCIe Gen3 I/O Drawer adds 10 PCIe slots (6-core or 8-core)
- Ethernet: Quad 1 Gbt in PCIe slot
- Integrated ports: USB (4/5), Serial (1), HMC (2)
- Internal Storage
 - DVD
 - 12 SFF Bays -- Split Backplane: 6 + 6
 - or 18 SFF Bays with 7GB write cache
- Hypervisor: PowerVM
- OS: AIX, IBM i 7.1 or later (P05/P10 software tier), Linux 3 Yr Warranty





POWER8 2S4U Scale-out System

Power S824

- Single Socket populated
 - Cores: 6 (3.8 GHz) or 8 (4.1 GHz)
 - Memory: Up to 1TB
 - Slots: 7 PCle Gen3 full-high (Hotplug)
- Both Sockets populated
 - Cores: 12 (3.8 GHz), 16 (4.1 GHz), or 24 (3.5 GHz)
 - Memory: Up to 2TB
 - Slots: 11 PCle Gen3 full-high (Hotplug)
- * PCIe Gen3 I/O drawer adds up to 20 PCIe slots
- Ethernet: Quad 1 Gbt in PCIe slot
- Integrated ports: USB (4/5), Serial (1), HMC (2)
- Internal Storage
 - DVD
 - 12 SFF Bays -- Split Backplane: 6 + 6
 - or 18 SFF bays & 8 SSD bays with 7GB write cache
- Hypervisor: PowerVM
- OS: AIX, IBM i 7.1 or later (P20 software tier), Linux



3 Yr Warranty

POWER8 4U 2-Socket Comparison

	Power 740	POWER8
Processor	POWER7+	POWER8 4U
Sockets	2	2
Cores	12 / 16	16 / 20 / 24
Maximum Memory	1 TB @ 1066 MHz	2 TB @ 1600 MHz
Memory Cache	No	Yes
Memory Bandwidth	68 GB/sec	200 GB/sec
Memory DRAM Spare	No	Yes
IO Expansion Slots	Dual GX++	4 PCIe x16 G3 (SOD)
PCIe slots	5 PCIe x8 FH 4 PCIe x8 HH (opt)	7 PCle x8 FH 4 PCle x16 FH
PCIe Hot Plug Support	No	Yes
IO bandwidth	60 GB/sec	192 GB/sec
Base* Ethernet ports	Four 1 Gb	Four 1Gb or Two 10 Gb
SSD-only bays	N/A – use SFF bays	Up to 8 1.8-inch bays
SFF bays	6	12 or 18
Integrated SAS controller	PCIe Gen1 base	PCIe Gen3 base
SR-IOV Support	No	Yes
Service Processor	Generation 1	Generation 2

* Base uses one PCIe slot

2S2U Scale-out System

Power S822

- Single Socket populated
 - Cores: 6 (3.8 GHz) or 10 (3.4 GHz) or 8 (4.1 GHz)
 - Memory: Up to 512 GB *
 - PCIe Slots: 6 PCIe Gen3 LP (Hotplug)
- Both Sockets populated
 - Cores: 12 (3.8 GHz) or 20 (3.4 GHz) or 16 (4.1 GHz)
 - Memory: Up to 1 TB *
 - PCIe Slots: 9 PCIe Gen3 LP (Hotplug)
- Ethernet: Choice of 1Gb or 10Gb PCIe adapter
- Integrated ports: USB (4), Serial (1), HMC (2)
- Internal Storage
 - DVD
 - 12 SFF Bays -- Split Backplane: 6 + 6
 - or 8 SFF Bays & 6 1.8" SSD Bays with Easy Tier with 7GB write cache
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- OS: AIX, Linux (IBM i added Oct 2015)
 - * Half this memory maximum with 4.1GHz cores (no 64GB DIMMs) due to air cooling limitations. See following chart with additional cooling limitations and for SOD for water cooling.





Power S822 and IBM i

IBM



- IBM i 7.2 TR3 or IBM i 7.1 TR11
- Special terms/conditions
- Only P10 software tier (P20 used on 2-socket S824)
- S822 with or without PurePower
- Max 2 cores per partition -- multiple partitions per server supported
- All IBM i I/O virtualized through VIOS. No non-VIOS I/O.
 - No Async/Bisync PCIe adapters (can use IBM i 7.2 with OEM LANattached box for Async including Fax/400)
 - No Crypto cards
 - If using disk/SSD in system unit or EXP24S I/O drawer for IBM i it must use 4k byte sectors, not 5xx byte sectors
- CBU feature #0444 not announced Oct 2015

Plus normal 2U limitations of smaller physical server vs 4U server -- smaller memory, fewer PCIe slots, fewer PCIe I/O drawers, subset of PCIe I/O card as full-high cards won't fit including any PCIe SAS adapters with write cache.

Minimum code levels required: IBM i 7.2 TR 3 or IBM i 7.1 TR 11, VIOS 2.2.3.52, FW 840, if using HMC then HMC 840



Enterprise

Power E850 / E870 / E880 Enterprise Characteristics

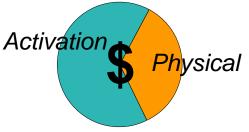


- Increased performance and scale compared to previous generation servers
- Capacity on Demand
 - Elastic CoD
 - Utility CoD
 - Trial CoD
- Power Integrated Facility for Linux
- Active Memory Mirroring for Hypervisor *
- ✓ E870/E880: Power Enterprise Pools
- E870/E880: PowerVM Enterprise included
- E880: Large block no-charge days with initial purchase

* optional for E850

Capacity on Demand for E870/E880

- Processor cores and/or memory activations
- Separating activation pricing from physical hardware
 - Makes redundant hardware more affordable
 - Eases budgeting buy when needed
 - Reduces planned downtime outages for upgrades
- Elastic CoD / Utility Cod
 - Use activations "by the day" or "by the minute" as needed
 - Elastic: pay quarterly if use; Utility pay after usage
 - Elastic example for Power E870 4.19 GHz
 - 1 add'l core + 16GB memory
 - 1 add'l cores licensing for IBM i and for other IBM Power System's controlled software
 - 1 add'l core's worth of 5250
 - ONLY \$196 per day



Power Enterprise Pools for E870/E880



Power E870 & 770+ Pool

- Max 48 servers
- In the same country
- Running 7.8 firmware or later
- Running any supported OS
- Max 1000 partitions



Power E880 & 780+ & 795 Pool

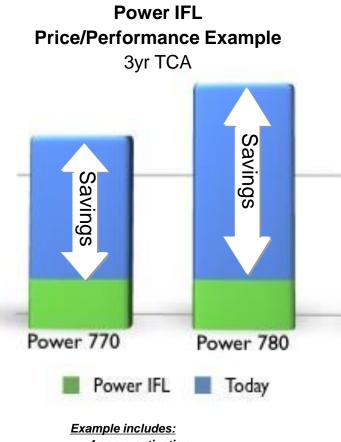
- Max 32 servers
- In the same country
- Running 7.8 firmware or later
- Running any supported OS
- Max 1000 partitions

Move processor and memory activations within a defined pool Move quickly, dynamically, non-disruptively Move at your convenience – without contacting IBM

PLUS also move specific Power software licensing entitlements

Power Integrated Facility for Linux

- For enterprise servers with processor cores and memory not permanently activated
 - Model E870 & Model E880
 - Model 770 & Model 780 & 795
- Package of activations & licensing
- Usable only for Linux workload
- Priced competitively vs. equivalent Linux stand-alone server
- Savings via lower priced activations, maintenance & licensing for Linux-only resource



- 4 cores activation
- 32 GB activations
- 4 PowerVM for Linux entitlements
- 4 RedHat Linux
- 3 yr 24x7 HWMA/SWMA

Prices are USA list price and are subject to change Reseller prices may vary.



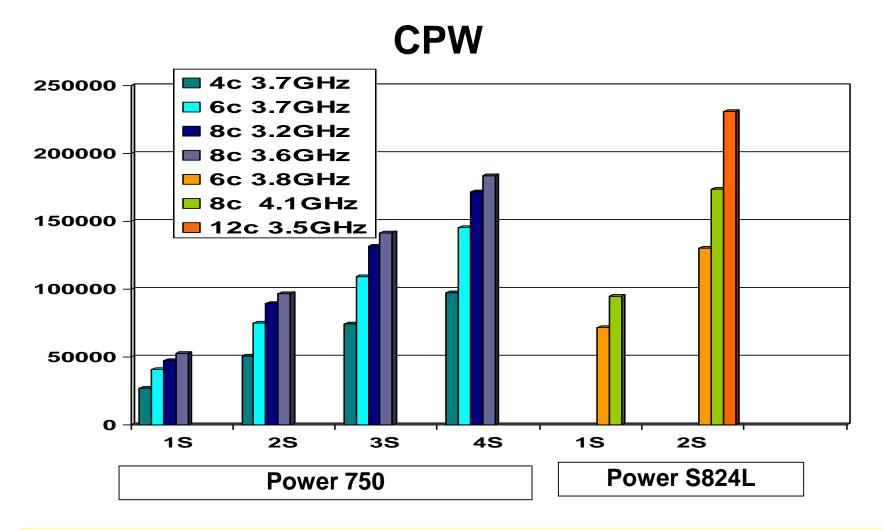
E850

Why not provide IBM i support on Power E850?

750 vs S824 Hardware Comparison Highlights

- CPW: Given most IBM i clients who are using a Power 750 are using smaller configurations, there is lots of CPW growth in Power S824
- Memory: S824 has 4x more memory capacity and it is 50% faster memory (1600MHz with L4 cache VS 1066MHz)
- PCIe:
 - S824 has newer, higher bandwidth PCIe Gen3 slots
 - Without considering PCIe I/O drawer, S824 has more PCIe slots
 - With PCIe I/O drawer, S824 has a very good number of high bandwidth slots (31), though less than the number of 750 2-4 socket maximum
 - S824 supports SR-IOV NIC
- Integrated Storage
 - S824 has optional integrated SAS controller with 7GB effectively write cache, more than 40X 750's 175MB.
 - S824 has up to 26 SAS bays in system unit for HDD/SSD. 3X more than 750
 - S824 can have up to 50 SAS bays run by integrated SAS controllers 6X more than 750

POWER7 750 (B mdl) vs POWER8 S824



Except perhaps for the 32-core Power 750 – lot's of room for CPW growth.

Power E870 & E880 Servers



Power E870:

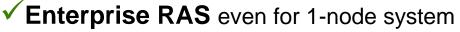
- Up to 80 cores
- 256 to 8TB Memory
- 1 or 2 nodes per system

Power E880:

- Up to 192 cores @ 4.02 GHz
- 256 to 16TB Memory
- 1 to 4 nodes per system





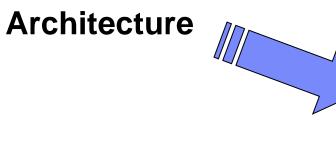


- System Control Unit ("midplane")
- ✓ Medium software tier
- ✓ 24x7 1-year warranty



POWER8 Enterprise Solutions









Packaging

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POWER8 Enterprise Solutions

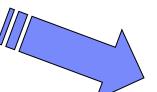




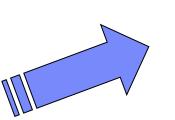
Midplane

- Service Processors
- Clocks
- Oscillators

Large Memory

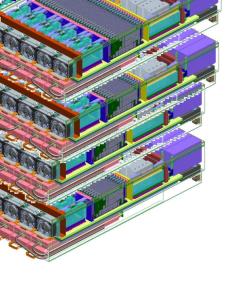


Midplan



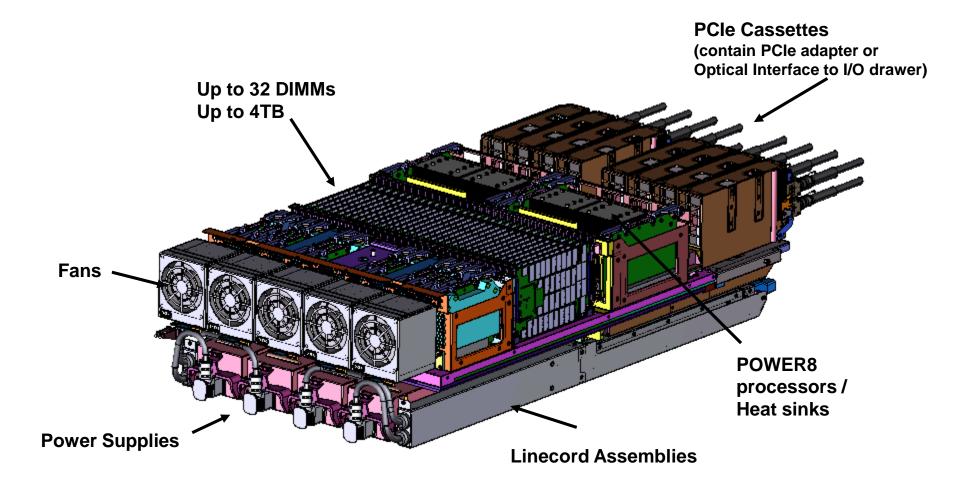


19" Rack Modular design Up to 4 CEC drawers Blindswap IO Adapters





POWER8 Processor Enclosure (CEC Drawer)



5U Enclosure



Power E870: 1 or 2 Nodes

12U in 19" rack

Node

MidPlane

Node



Power E880: 1, 2, 3 or 4 Nodes



Node

Node

MidPlane

Node

Node

3- and 4-node configurations planned availability June 2015

Power Scale Perspective

Power 770

Power 795

Power 780

POWER8 E870 Compares: 2-Node/Drawer System

	9117-MMD Power 770	POWER8 Enterprise 2 CEC Node- drawer	
CPU Sockets per Node/Drawer	4	4	
Max processor nodes/Drawers	4	2	
Max number sockets	16	8	
Max Cores	64	64 or 80	
Max Frequency	3.8 GHz	4 or 4.19 GHz	
Max Memory	1 TB per CEC Drw	4 TB per CEC Drw	
Memory per core	64 GB	62 or 50 GB	
Memory Bandwidth (peak)	272 GB/s per CEC Drw	922 GB/s per CEC Drw	
I/O Bandwidth (peak)	80 GB/s per CEC Drw (GX)	256 GB/s per CEC Drw (PCle Gen3)	
Max PCle I/O drws	16 (4 per Node)	8 (4 per Node)	
Max PCIe I/O Slots	160 - in IO drws 24 - internal	96 – in IO drws 0 - internal	
IBM i levels supported	IBM i 6.1 and later	IBM i 7.1 and later	

* SOD = statement of direction – represents IBM plans shared publically. As always plans subject to change.

POWER8 E880 Compares: 4-Node/Drawer System

	9117-MMD Power 770	9179-MHD Power 780	POWER8 Enterprise 4 CEC Node- drawer
CPU Sockets per Node/Drawer	4	4	4
Max processor nodes/Drawers	4	4	4
Max number sockets	16	16	16
Max Cores	64	128	192
Max Frequency	3.8 GHz	3.7 GHz	4.35
Max Memory	1 TB per CEC Drw	1 TB per CEC Drw	4 TB per CEC Drw
Memory per core	64 GB	32 GB	128 or 85 GB
Memory Bandwidth (peak)	272 GB/s per CEC Drw	272 GB/s per CEC Drw	922 GB/s per CEC Drw
Memory Bandwidth per core (peak)	17 GB/sec	8.5 GB/sec	19 GB/sec
I/O Bandwidth (peak)	80 GB/s per CEC Drw (GX)	80 GB/s per CEC Drw (GX)	256 GB/s per CEC Drw (PCle Gen3)
Max PCIe I/O drws	16 (4 per Node)	16 (4 per Node)	16 (4 per Node)
Max PCIe I/O Slots	160 - in IO drws 24 - internal	160 - in IO drws 24 - internal	192
IBM i levels supported	IBM i 6.1 and later	IBM i 6.1 and later	IBM i 7.1 and later

PCIe I/O Drawer

POWER8 PCIe Gen3 IO Drawer

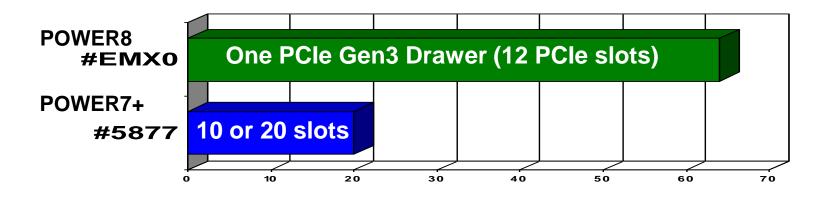


- 4U in standard 19" rack
- 6 or 12 PCIe Gen3 slots
 - Full-High, Full-Length
 - 1/3rd x16 slots and 2/3rd x8 slots
- Dual fiber optic cables connect to POWER8 CEC
 - Connects to x16 slot in CEC



IO Bandwidth (Comparing I/O Drawers)

Total drawer GB/Sec

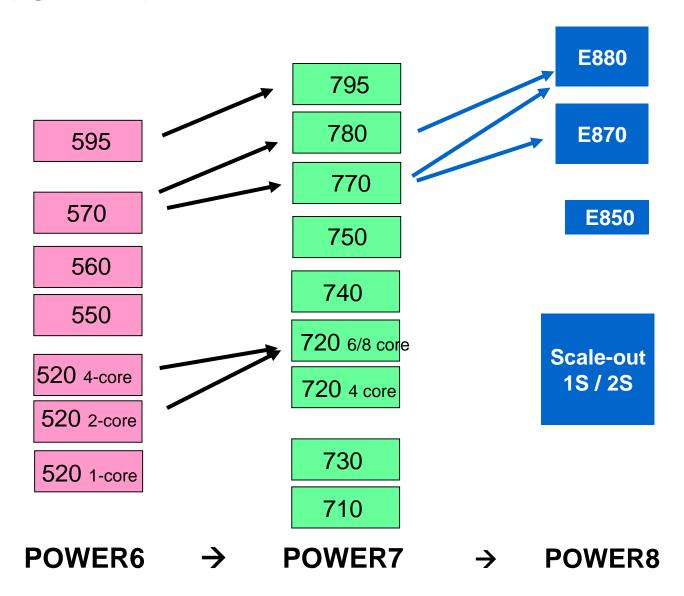


POWER8 PCIe-attached Gen3 I/O drawer has two fan-out modules and each fan-out module has 32GB/s

POWER7 12X-attached PCIe I/O drawer = #5877 or #5802 One or two #5877 or #5802 can share a single GX++ slot's 20GB/s bandwidth

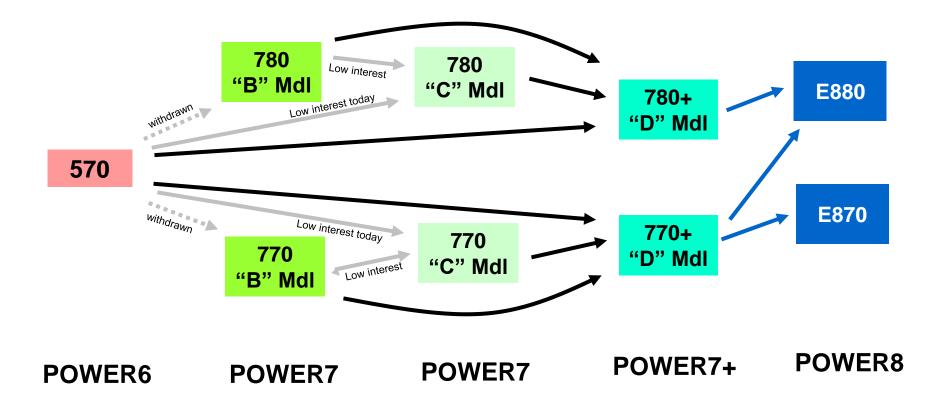
I/O Loop (GX+) Technology Transitions							
	POWER5	POWER6	POWER7	POWER8 Not GX based			
	HSL / RIO w/ PCI-X	HSL / RIO w/ PCI-X 12X SDR w/ PCI-X 12X DDR w/ PCIe	 12X SDR w/ PCI-X 12X DDR with PCIe	 PCle3			

Model Upgrades (Same Serial Number)

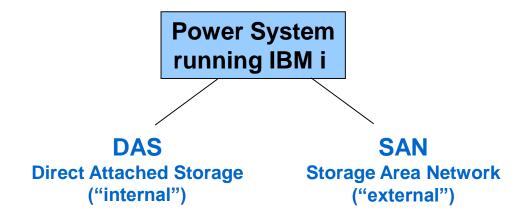




770/780 Model Upgrades (Same Serial Number)

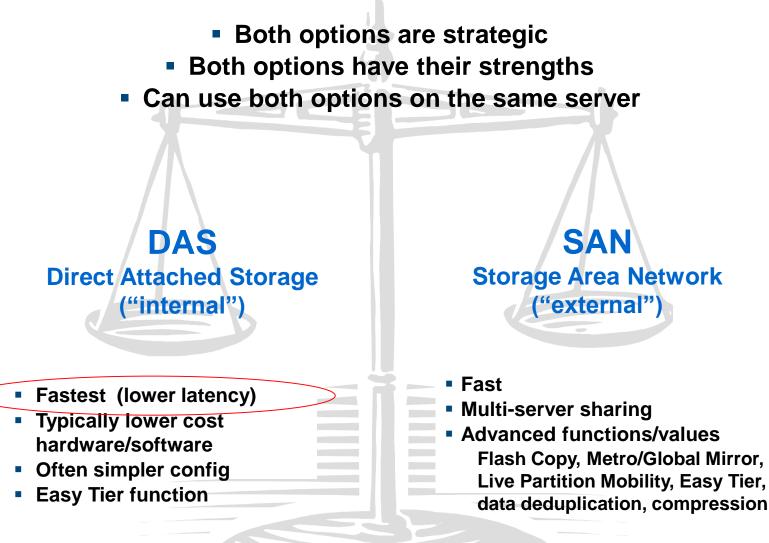


DAS or SAN ?



- Both options are strategic
- Both options have their strengths
- Can use both options on the same server
- Application independent
 - -Ignoring operational options

DAS & SAN - Two Good Options



POWER8 SAS SFF HDD Options as of Nov 2015

SFF-3 HDD	Block size	Formatted with 512 or 4096 byte sectors *	Formatted with 528 or 4224 byte sectors
10k	5xx	300 GB *	283 GB
10k	5xx	600 GB *	571 GB
10k	5xx	1.2 TB *	1.1 TB
10k	4k	600 GB *	571 GB
10k	4k	1.2 TB *	1.1 TB
10k	4k	1.8 TB *	1.7 TB
15k	5xx	146 GB *	139 GB
15k	5xx	300 GB *	283 GB
15k	5xx	600 GB *	571 GB
15k	4k	300 GB *	283 GB
15k	4k	600 GB *	571 GB

* POWER8 SFF HDD shipped from IBM formatted in 528 or 4224 byte sectors. They can be reformatted to 512 or 4096 by the client if the extra protection is not desired.

4k drives (HDD or SSD) can NOT be reformatted to 5xx drives.

4k drives and 5xx drives can NOT be mixed on the same array. True for both HDD and SSD.

POWER8 SAS SFF HDD Options as of Nov 2015

SFF-3 HDD 10k	Block size	Formatted with 512 or 4096 byte sectors *	Formatted with 528 or 4224 byte sectors	
	5xx		city drives approaching end of n	harketing in
10k	5xx	600 GB *	571 GB	
10k	5xx	1.2 TB *	1.1 TB	
10k	4k	600 GB *	571 GB	
10k	4k	1.2 TB * 4k more strat	tegic than 5xx	
10k	4k	1.8 TB *	1.7 TB	
15k	5xx	146 GB [*] Smaller capac	ty drives approaching end of n	narketing lif
15k	5xx	300 GB *	283 GB	
15k	5xx	600 GB *	571 GB	
15k	4k	300 GB *	rategic than 5xx	
15k	4k	600 GB *		

* POWER8 SFF HDD shipped from IBM formatted in 528 or 4224 byte sectors. They can be reformatted to 512 or 4096 by the client if the extra protection is not desired.

4k drives (HDD or SSD) can NOT be reformatted to 5xx drives.

4k drives and 5xx drives can NOT be mixed on the same array. True for both HDD and SSD.

eMLC SSD Generations

2.5-inch (SFF)		IO OPERATIONS PER SECOND (IOPS)		Throughput (MB/s)		Latency - Response Time (ms)	
	SSD	Random Read	Random Write	Random Mixed Read/Write	Read	Write	Random Mixed Read/Write
Gen 1	177GB	15 k	4 k	11 k (70%-30%)	170 MB	64 MB (24-123)	0.31 ms (70%-30%)
Gen 2	387GB	39 k	22 k	24 k (70%-30%)	340 MB	375 MB	0.25 ms (70%-30%)
Gen 3	387GB 775GB	80 k	49 k	58 k (60%-40%)	340 MB	450 MB	0.15 ms (60%-40%)

<u>.</u>	For grins … 15k rpm HDD	0.12 - 0.4 k	0.12 - 0.4 k	0.12 - 0.4 k	~175 MB	~175 MB	8.3 – 2.5 ms
----------	----------------------------	--------------	--------------	--------------	---------	---------	--------------

Note these are single drive specific measurements reflecting sustained drive workloads (not burst). The values assume 528 byte sectors running RAID-0 with no protection. Hypothetically if measured with unsupported 512 byte sectors, values would be higher. The values are highly workload dependent. Factors such as read/write mix, random/non-random data, drive cache hits/misses, data compressibility in the drive controller, large/small block, type of RAID or mirroring protection, etc will change these values. The choice of which SAS controller/adapter is running the drive can also impact these values. These values produced by a server with plenty of processor, memory and controller resources to push this much I/O into the SSD. Most client system applications don't push SSD nearly this hard. Latency measurements using OLTP1 60/40 random 4k transfers.

SSD Driving SAS Adapter Technology

Comparing large cache SAS Adapters





PCIe SAS – PCIe Gen 3 1Q 2014 Designed for newest SSD 800k-ish IOPS in Gen1 slot * Nearly 1M IOPS in Gen2 slot Up to 96 HDD Up to 48 SSD

* restricted by PCIe Gen1 slot in which the adapter first announced

400k IOPs





PCI-X SAS 2Q 2009 Est 70-80k IOPS Up to 48-60 HDD Also can do some SSD PCIe SAS – PCIe Gen 2 4Q 2011 1st SAS adapter designed fo SSD 300-400k IOPS Up to 72 HDD Up to 24 SSD

> SAS adapter technology – designed by IBM Power Systems with Power Systems reliability, ruggedness, integrity, performance,

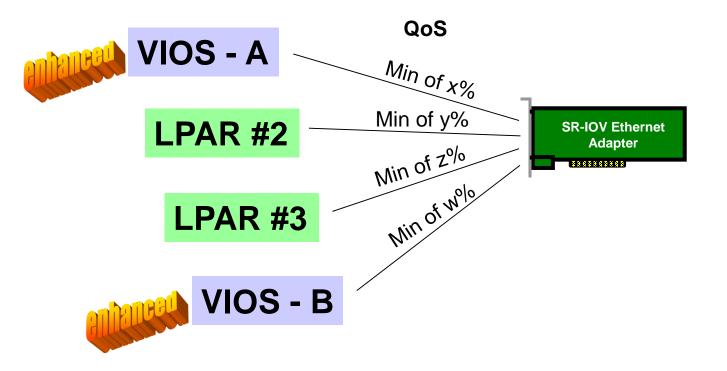
80k IOPs

FlashSystem and IBM i Support



- Native support with IBM i 7.2 TR2 or later for FlashSystem 900 or
- Also supported when "behind" an SVC (including FlashSystem V9000 ... "non-native"

SR-IOV Virtualization Enhanced Oct 2015





IBM Power Systems

Power Hardware Update



Mark Olson olsonm@us.ibm.com

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